BUK9629-100B

N-channel TrenchMOS logic level FET

Rev. 02 — 9 February 2011 **Product data sheet**

1. Product profile

1.1 General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

1.2 Features and benefits

- AEC Q101 compliant
- Low conduction losses due to low on-state resistance
- Suitable for logic level gate drive sources
- Suitable for thermally demanding environments due to 175 °C rating

1.3 Applications

- 12 V, 24 V and 42 V loads
- Automotive systems
- General purpose power switching
- Motors, lamps and solenoids

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 175$ °C	-	-	100	V
I_D	drain current	V_{GS} = 5 V; T_{mb} = 25 °C; see Figure 1; see Figure 3	-	-	46	A
P_{tot}	total power dissipation	T_{mb} = 25 °C; see Figure 2	-	-	157	W
Static characteristics						
R_{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 25 A; T_j = 25 °C	-	22	27	mΩ
		V_{GS} = 5 V; I_D = 25 A; T_j = 25 °C; see Figure 6; see Figure 7	-	24	29	mΩ

Table 1. Quick reference data *...continued*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	I_D = 46 A; $V_{sup} \leq$ 100 V; R_{GS} = 50 Ω; V_{GS} = 5 V; $T_{j(init)}$ = 25 °C; unclamped	-	-	152	mJ
Dynamic characteristics						
Q_{GD}	gate-drain charge	V_{GS} = 5 V; I_D = 25 A; V_{DS} = 80 V; T_j = 25 °C; see Figure 8	-	13	-	nC

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	mb	D
2	D	drain[1]	2	G
3	S	source	1 3	mbb076 S
mb	D	mounting base; connected to drain		

SOT404 (D2PAK)

[1] It is not possible to make a connection to pin 2.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK9629-100B	D2PAK	plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)	SOT404

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 175$ °C	-	100	V
V_{DGR}	drain-gate voltage	R_{GS} = 20 kΩ	-	100	V
V_{GS}	gate-source voltage		-15	15	V
I_D	drain current	T_{mb} = 25 °C; V_{GS} = 5 V; see Figure 1; see Figure 3	-	46	A
		T_{mb} = 100 °C; V_{GS} = 5 V; see Figure 1	-	32	A
I_{DM}	peak drain current	T_{mb} = 25 °C; pulsed; $t_p \leq 10$ µs; see Figure 3	-	186	A
P_{tot}	total power dissipation	T_{mb} = 25 °C; see Figure 2	-	157	W
T_{stg}	storage temperature		-55	175	°C
T_j	junction temperature		-55	175	°C
Source-drain diode					
I_S	source current	T_{mb} = 25 °C	-	46	A
I_{SM}	peak source current	pulsed; $t_p \leq 10$ µs; T_{mb} = 25 °C	-	186	A
Avalanche ruggedness					
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	I_D = 46 A; $V_{sup} \leq 100$ V; R_{GS} = 50 Ω; V_{GS} = 5 V; $T_{j(init)}$ = 25 °C; unclamped	-	152	mJ

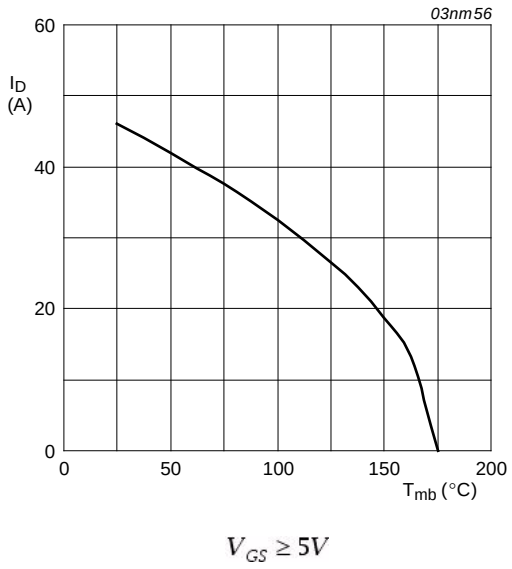


Fig 1. Normalized continuous drain current as a function of mounting base temperature

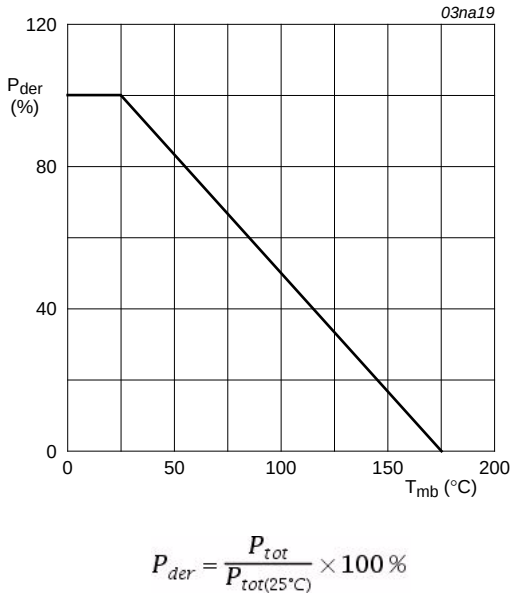
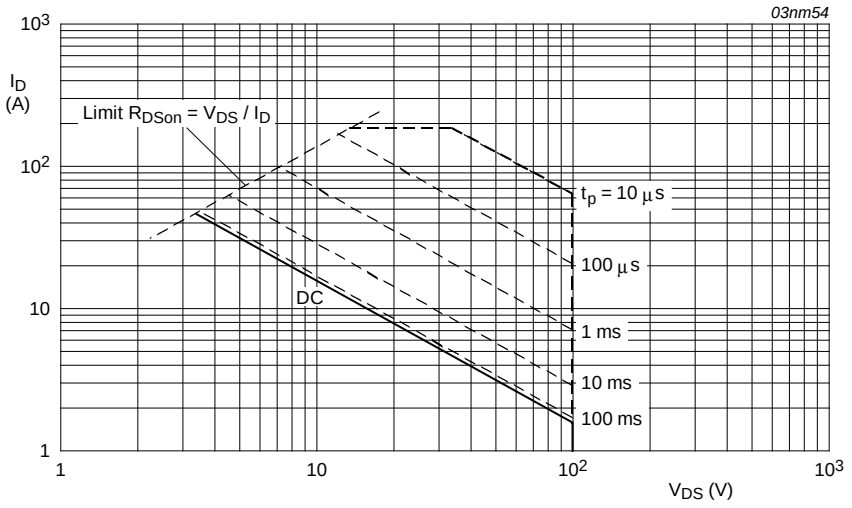


Fig 2. Normalized total power dissipation as a function of mounting base temperature



$T_{mb} = 25°C; I_{DM}$ is single pulse

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	-	0.95	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	minimum footprint; mounted on a printed-circuit board	-	50	-	K/W

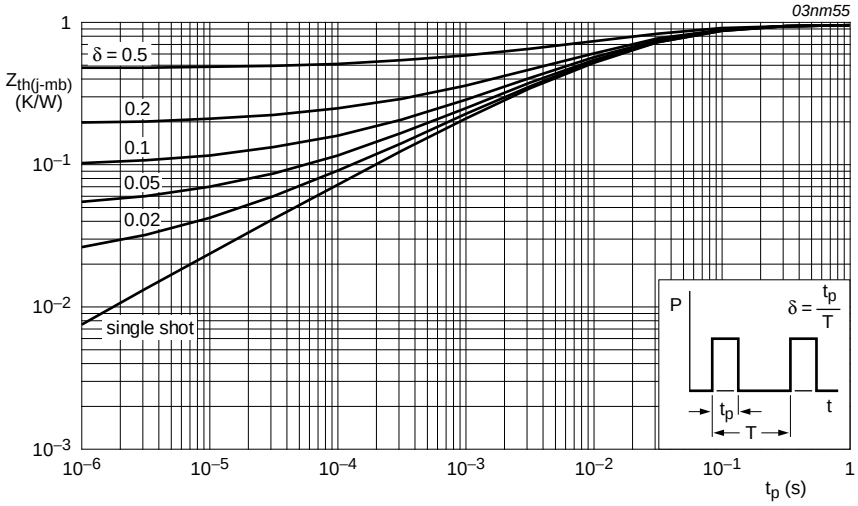


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

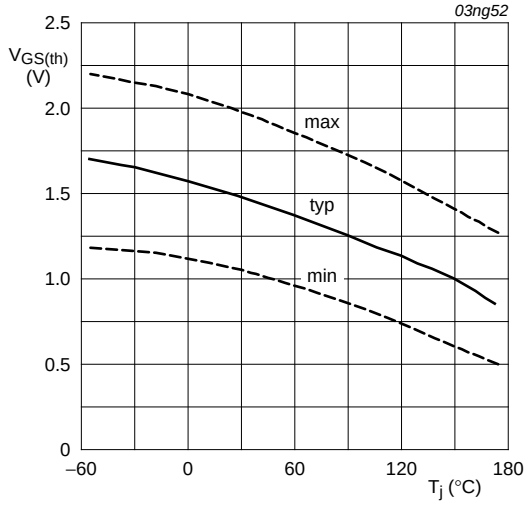
6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 0.25 mA; V_{GS} = 0 V; T_j = 25 °C	100	-	-	V
		I_D = 0.25 mA; V_{GS} = 0 V; T_j = -55 °C	89	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	I_D = 1 mA; V_{DS} = V_{GS}; T_j = 25 °C; see Figure 5	1.1	1.5	2	V
		I_D = 1 mA; V_{DS} = V_{GS}; T_j = -55 °C; see Figure 5	-	-	2.3	V
		I_D = 1 mA; V_{DS} = V_{GS}; T_j = 175 °C; see Figure 5	0.5	-	-	V
I_{DSS}	drain leakage current	V_{DS} = 100 V; V_{GS} = 0 V; T_j = 175 °C	-	-	500	µA
		V_{DS} = 100 V; V_{GS} = 0 V; T_j = 25 °C	-	0.02	1	µA
I_{GSS}	gate leakage current	V_{GS} = 15 V; V_{DS} = 0 V; T_j = 25 °C	-	2	100	nA
		V_{GS} = -15 V; V_{DS} = 0 V; T_j = 25 °C	-	2	100	nA
R_{DSon}	drain-source on-state resistance	V_{GS} = 4.5 V; I_D = 25 A; T_j = 25 °C	-	-	32	mΩ
		V_{GS} = 5 V; I_D = 25 A; T_j = 175 °C; see Figure 6; see Figure 7	-	-	75	mΩ
		V_{GS} = 10 V; I_D = 25 A; T_j = 25 °C	-	22	27	mΩ
		V_{GS} = 5 V; I_D = 25 A; T_j = 25 °C; see Figure 6; see Figure 7	-	24	29	mΩ
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	I_D = 25 A; V_{DS} = 80 V; V_{GS} = 5 V; T_j = 25 °C; see Figure 8	-	33	-	nC
Q_{GS}	gate-source charge		-	7	-	nC
Q_{GD}	gate-drain charge		-	13	-	nC
C_{iss}	input capacitance	V_{GS} = 0 V; V_{DS} = 25 V; f = 1 MHz; T_j = 25 °C; see Figure 9	-	3270	4360	pF
C_{oss}	output capacitance		-	236	283	pF
C_{rss}	reverse transfer capacitance		-	103	141	pF
$t_{d(on)}$	turn-on delay time	V_{DS} = 30 V; R_L = 1.2 Ω; V_{GS} = 5 V; $R_{G(ext)}$ = 10 Ω; T_j = 25 °C	-	30	-	ns
t_r	rise time		-	86	-	ns
$t_{d(off)}$	turn-off delay time		-	96	-	ns
t_f	fall time		-	46	-	ns
L_D	internal drain inductance	from upper edge of drain mounting base to centre of die; T_j = 25 °C	-	2.5	-	nH
		from drain lead 6 mm from package to centre of die; T_j = 25 °C	-	4.5	-	nH
L_S	internal source inductance	from source lead to source bond pad; T_j = 25 °C	-	7.5	-	nH

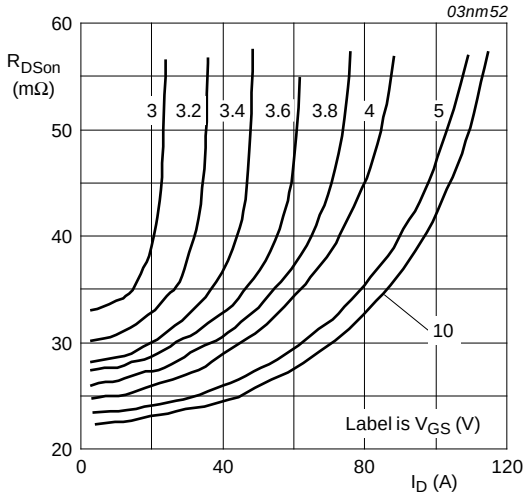
Table 6. Characteristics *...continued*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Source-drain diode						
V_{SD}	source-drain voltage	I_S = 25 A; V_{GS} = 0 V; T_j = 25 °C; see Figure 10	-	0.85	1.2	V
t_{rr}	reverse recovery time	I_S = 20 A; dI_S/dt = -100 A/µs; V_{GS} = -10 V; V_{DS} = 30 V; T_j = 25 °C	-	114	-	ns
Q_r	recovered charge		-	196	-	nC



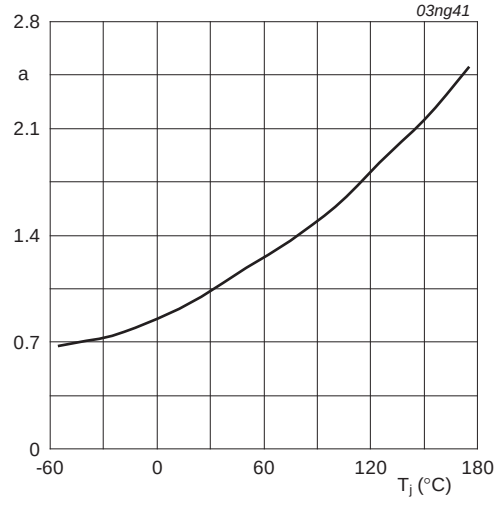
$I_D = 1mA; V_{DS} = V_{GS}$

Fig 5. Gate-source threshold voltage as a function of junction temperature



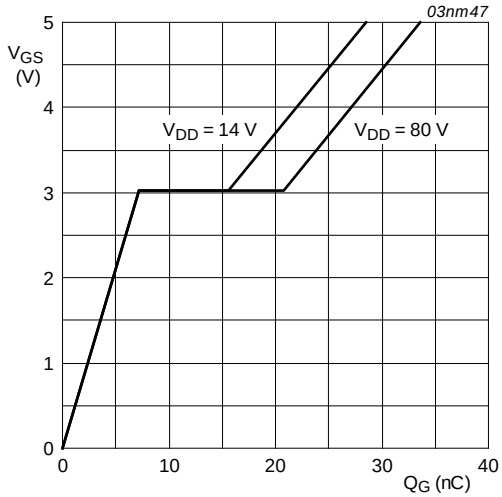
$T_j = 25°C$

Fig 6. Drain-source on-state resistance as a function of gate-source voltage; typical values



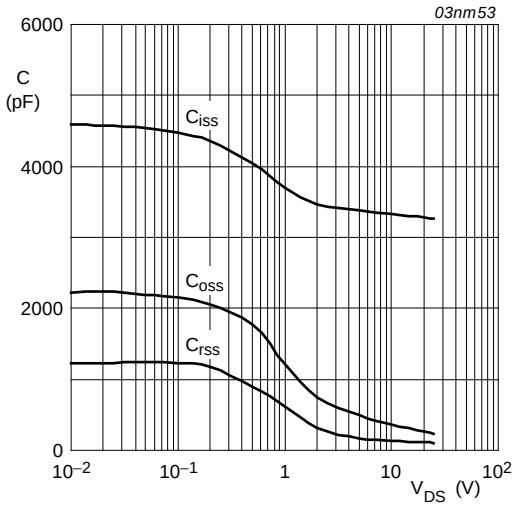
$$a = \frac{R_{DSon}}{R_{DSon(25°C)}}$$

Fig 7. Normalized drain-source on-state resistance factor as a function of junction temperature



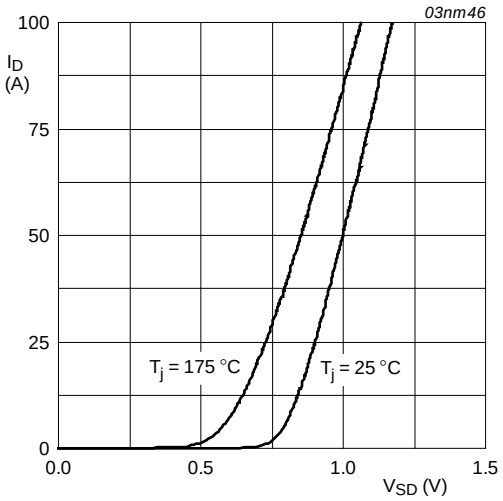
$T_j = 25°C; I_D = 25A$

Fig 8. Gate-source threshold voltage as a function of junction temperature



$V_{GS} = 0V; f = 1MHz$

Fig 9. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

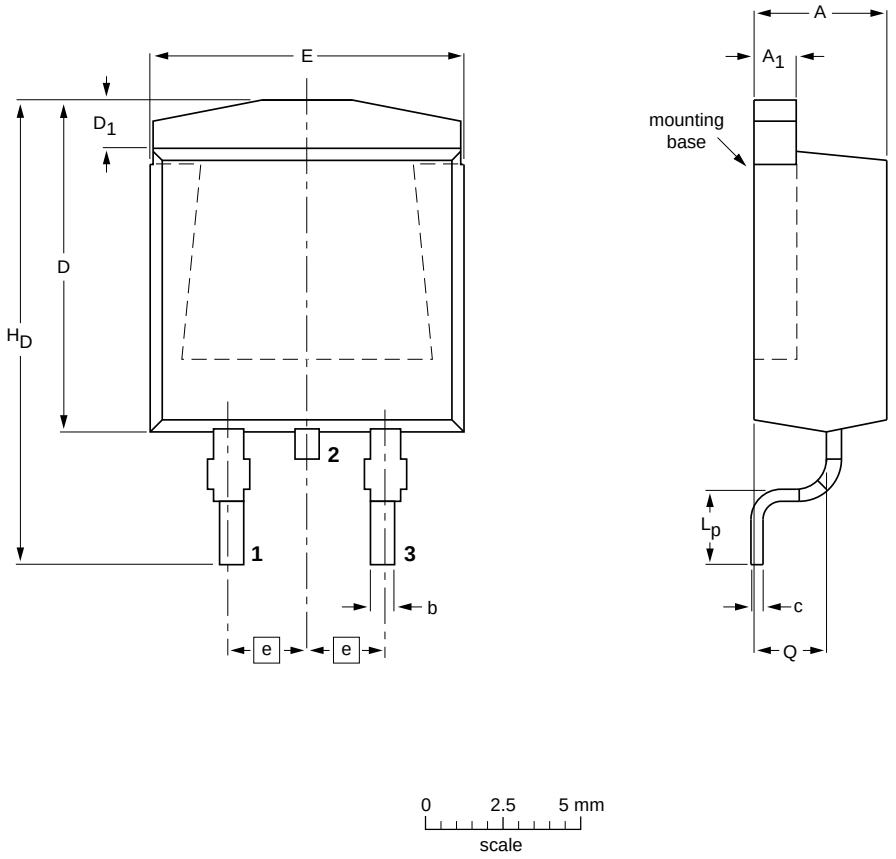


$V_{GS} = 0V$

Fig 10. Source current as a function of source-drain voltage; typical values

7. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) **SOT404**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b	c	D max.	D_1	E	e	L_p	H_D	Q
mm	4.50 4.10	1.40 1.27	0.85 0.60	0.64 0.46	11	1.60 1.20	10.30 9.70	2.54	2.90 2.10	15.80 14.80	2.60 2.20

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT404						~~05-02-11~~ 06-03-16

Fig 11. Package outline SOT404 (D2PAK)

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BUK9629-100B v.2	20110209	Product data sheet	-	BUK95_9629_100B v.1
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Type number BUK9629-100B separated from data sheet BUK95_9629_100B v.1.			
BUK95_9629_100B v.1 (9397 750 11249)	20030418	Product data	-	-

9. Legal information

9.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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11. Contents

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